DuPont™ PlasmaSolv®
Post-Etch Residue Remover
Made with HDA® technology to most effectively remove residue, increase yields and reliability

**Product Description**
DuPont™ PlasmaSolv® post-etch residue removers are made with HDA® high-performance hydroxylamine-based cleaning technology. HDA® technology comprises aqueous organic mixtures formulated to effectively remove residues from substrate surfaces after via, poly and metal etch processes used in the microelectronics industry. Effective cleaning after dry etch process steps helps achieve high manufacturing yields and more reliable semiconductor devices for the higher performance and lower power consumption needed for cell phones, games, computers and other electronic devices. DuPont™ PlasmaSolv® products perform at low operating temperatures, well below the flashpoint of the chemistries, providing a safe chemical process as well as extending bath life.

**DuPont™ PlasmaSolv® post-etch residue removers include:**

**EKC220™**
This product is similar to EKC265™, but utilizes hydroxylamine more efficiently as a result of product optimization. Originally developed to address Ti undercut with a cost effective formulation.

**EKC245™**
Specifically designed to clean post-etch residues generated during the volume production of high capacity DRAM devices. Applications include residue removal post HBr-polysilicon etch and post metal etch.

**EKC265™**
The initial product in the Plasmasolv® series formulated to remove photoresist residue generated after via and metal etch processes. Effective with or without oxygen ash processing.

**EKC270™**
Post-etch residue remover with improved Ti compatibility. Formulated to remove ashed photoresist residue, organic polymer, and organometallic etch residue while maintaining optimum metal stack integrity.

**EKC270™-T**
Post-etch residue remover with improved compatibility for Ti, W and Al on polysilicon, metal and high aspect ratio vias. Specifically formulated to meet the needs of customers who require a single chemistry for multiple post-etch residue cleaning applications due to its robust process window.
For more information on DuPont™ PlasmaSolv® or other DuPont products, please visit our website.

ekctech.dupont.com

Table 1. DuPont™ PlasmaSolv® Post-Etch Residue Remover Hydroxylamine (HDA®) Product Comparison

<table>
<thead>
<tr>
<th>Product</th>
<th>Wet Bench and Spray Tool Compatibility</th>
<th>Process Temperature</th>
<th>Intermediate Rinse</th>
<th>Comments</th>
</tr>
</thead>
<tbody>
<tr>
<td>EKC220&quot;</td>
<td>Yes</td>
<td>65 ºC</td>
<td>EKC4000&quot; IPA or NMP</td>
<td>Mildest of HDA® formulations, but still powerful enough to remove post plasma etch residue on vias and metal lines as well as photoresist.</td>
</tr>
<tr>
<td>EKC245&quot;</td>
<td>Yes</td>
<td>65 ºC</td>
<td>EKC4000&quot; IPA or NMP</td>
<td>Most powerful of HDA® formulations. Designed to remove tough post-etch residue on DRAM products and HBr etched polysilicon.</td>
</tr>
<tr>
<td>EKC265&quot;</td>
<td>Yes</td>
<td>65 ºC</td>
<td>EKC4000&quot; IPA or NMP</td>
<td>Industry leading HDA® formulation developed for the removal of post plasma etch residues on poly, vias and metal lines as well as organic (photoresist) residue.</td>
</tr>
<tr>
<td>EKC270&quot;</td>
<td>Yes</td>
<td>70 ºC</td>
<td>EKC4000&quot; IPA or NMP</td>
<td>Similar cleaning performance to EKC265&quot;, but with better compatibility to sensitive metals like titanium.</td>
</tr>
<tr>
<td>EKC270-T&quot;</td>
<td>Yes</td>
<td>70 ºC</td>
<td>IPA or NMP</td>
<td>Powerful HDA® formulation developed for high volume foundry etch applications with compatibility to many sensitive metals.</td>
</tr>
</tbody>
</table>

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